METHOD FOR THIN FILM ENCAPSULATION (TFE) OF A MICROELECTROMECHANICAL SYSTEM (MEMS) DEVICE AND THE MEMS DEVICE ENCAPSULATED THEREOF

ABSTRACT

A method for thin film encapsulation (TFE) of a microelectromechanical system (MEMS) device, including providing a substrate; forming a MEMS device on the substrate; forming one or more etching channels adjacent to the MEMS device; providing one or more cavities below the MEMS device; and forming one or more cavities above the MEMS device.

FIG. 3

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